MODEL: HSS25-B20-P51 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 or TO-218 package
- solder pin
- aluminum alloy

RoHS

MODEL

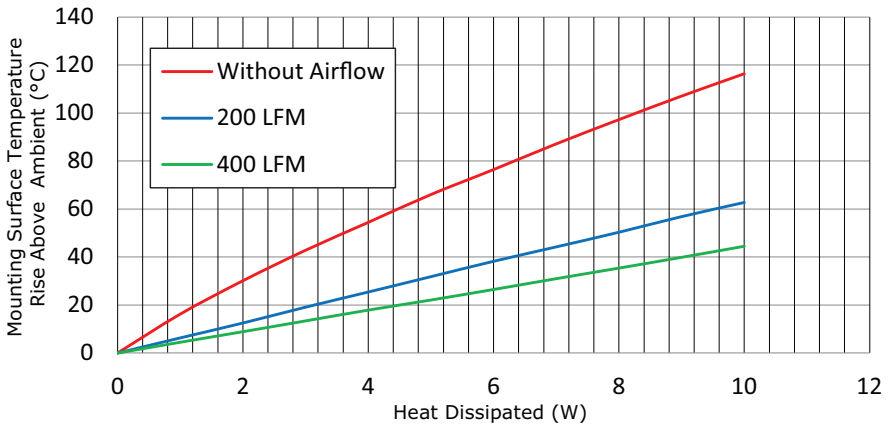
	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS25-B20-P51	12.75	16.2	6.3	4.5	5.88

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	16.2	6.3	4.5
2	30.1	12.5	8.9
3	42.8	19.1	13.4
4	54.4	25.4	17.9
5	66.0	31.8	22.1
6	76.4	38.2	26.5
7	87.1	44.2	31.0
8	97.2	50.3	35.4
9	107.0	56.8	39.9
10	116.3	62.7	44.5

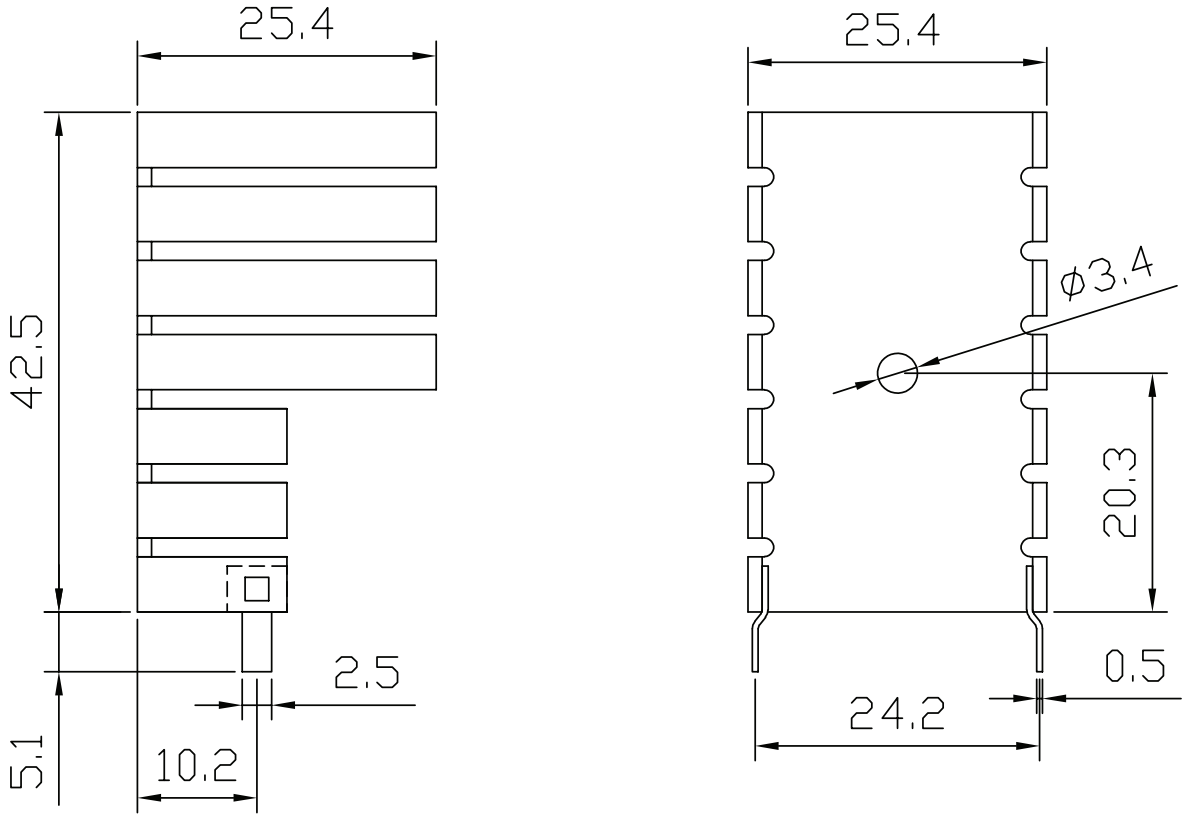
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	9.3 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/20/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.